



PK754 (v1.0) July 10, 2015

100% Material Declaration Data Sheet Spartan®-6 Cu Wire FGG484 Package

Average Weight: 2.300 g

| Component | Substance Description | CAS# or Description | % of Component | Use in Product | Component Weight/ Substance Weight (in grams) | Component % of Total |
|----------------------------|-----------------------|---------------------|----------------|-----------------|---|-------------------------|
| Silicon Die | | | | | 0.038245 | 1.663% |
| | Silicon | 7440-21-3 | 100.00 | Main material | 0.038245 | |
| Die Attach Material | | | | | 0.007051 | 0.307% |
| | Silver | 7440-22-4 | 77.50 | Main material | 0.005465 | |
| | Bismaleimide monomer | Trade Secret | 15.00 | Main material | 0.001058 | |
| | Acrylate monomer | Trade Secret | 7.50 | Main material | 0.000529 | |
| Copper Wire | | | | | 0.007385 | 0.321% |
| | Cu | 7440-50-8 | 98.25 | Main material | 0.007256 | |
| | Pd | 7440-05-3 | 1.75 | Dopant | 0.000129 | |
| Mold Compound | | | | | 0.851079 | 37.003% |
| | Epoxy Resin | Trade secret | 3.00 | Main material | 0.025532 | |
| | Phenol Resin A | 9003-35-4 | 3.00 | Main material | 0.025532 | |
| | Phenol Resin B | Trade secret | 3.00 | Main material | 0.025532 | |
| | Silica(Amorphous) A | 60676-86-0 | 72.45 | Filler | 0.616607 | |
| | Silica(Amorphous) B | 7631-86-9 | 15.00 | Filler | 0.127662 | |
| | Metal Hydroxide | Trade secret | 3.00 | Flame retardant | 0.025532 | |
| | Carbon black | 1333-86-4 | 0.55 | Color agent | 0.004681 | |
| Solder Balls | | | | | 0.404317 | 17.579% |
| | Tin (Sn) | 7440-31-5 | 96.50 | Main material | 0.390166 | |
| | Silver (Ag) | 7440-22-4 | 3.00 | Main material | 0.012130 | |
| | Copper (Cu) | 7440-50-8 | 0.50 | Main material | 0.002022 | |

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| Component | Substance Description | CAS# or Description | % of Component | Use in Product | Component Weight/ Substance Weight (in grams) | Component % of Total |
|-----------|---------------------------------------|--|----------------|----------------|---|-------------------------|
| Substrate | | | | | 0.991923 | 43.127% |
| | Au | 7440-57-5 | 0.867 | Main material | 0.008601 | |
| | Ni | 7440-02-0 | 8.418 | Main material | 0.083503 | |
| | Cu foil | 7440-50-8 | 2.577 | Main material | 0.025566 | |
| | Cu plating | 7440-50-8 | 16.109 | Plating | 0.159788 | |
| | Continuous Filament Fiber Glass | 65997-17-3 | 20.029 | Glass Fiber | 0.198668 | |
| | BT Core | 7440-50-8 N/A | 35.003 | Core | 0.347208 | |
| | Solder Mask | 14807-96-6 7727-43-7 7631-86-9 34590-94-8 91-20-3 85954-11-6 N/A | 12.541 | Solder mask | 0.124399 | |
| | Prepregs | NA | 4.455 | Prepregs | 0.044191 | |

Revision History

The following table shows the revision history for this document.

| Date | Version | Description of Revisions |
|---------|---------|--------------------------|
| 7/10/15 | 1.0 | Initial Xilinx release |

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